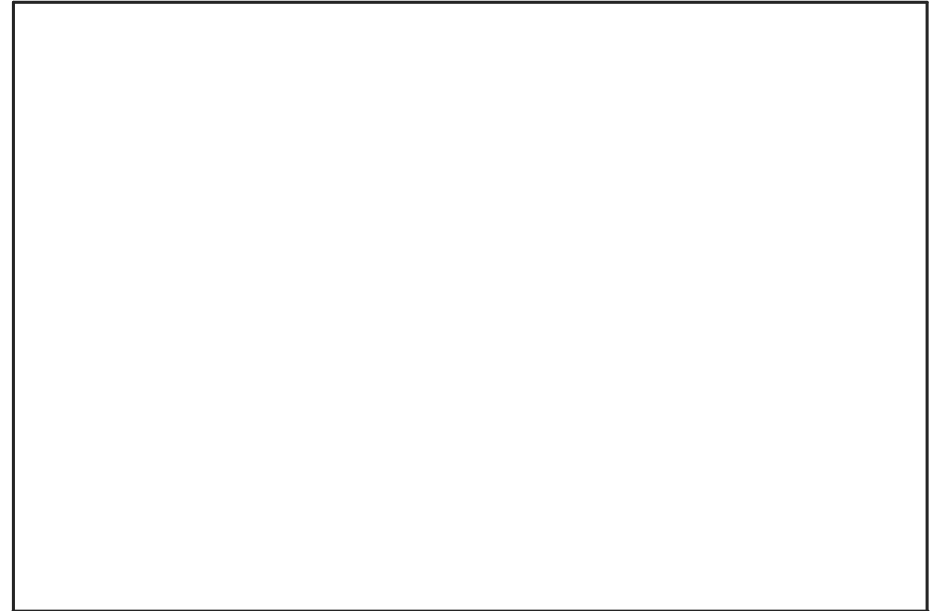


ZZ4 ■ These assemblies must comply with workmanship standard
 ZZ3 ■ These assemblies must be clean and free from flux and
 ZZ2 ■ These assemblies are ESD sensitive, ESD precautions s

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00645	REV: E1	SVN REV: Not In VersionControl
	TID #: 00645		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/1/2015	1:21:46 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00645	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00645		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/1/2015 1:21:47 PM	TEXAS INSTRUMENTS	

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